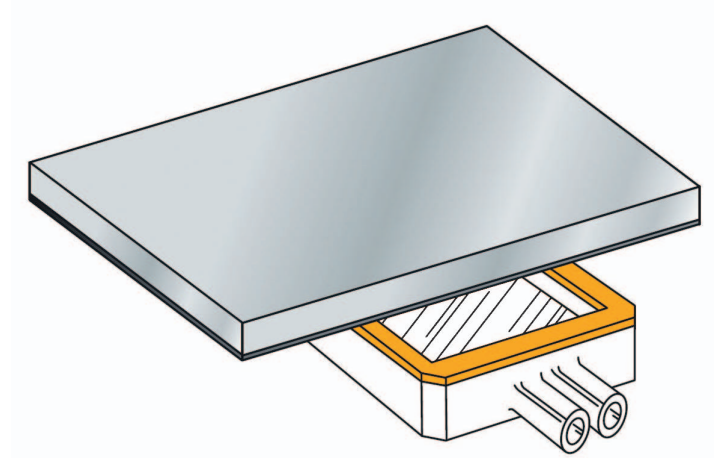
SikaMelt®-9185 IA
THE OPTIMAL SOLUTION FOR JUNCTION BOX BONDING

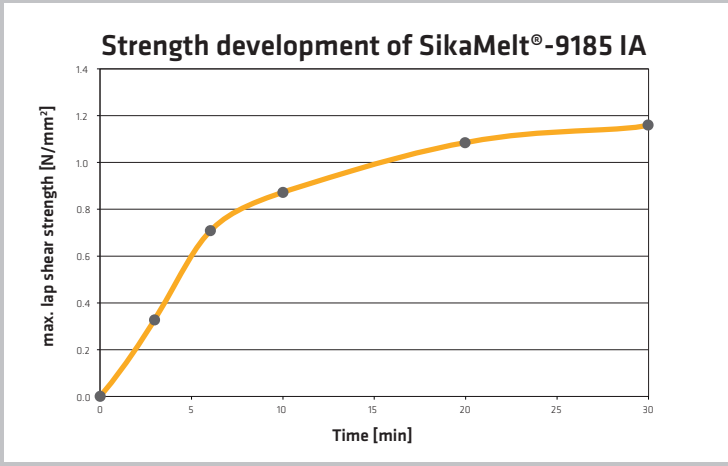
BUILDING TRUST

SikaMelt®-9185 IA

SikaMelt®-9185 IA is a one-component, reactive hot melt with low density. The adhesive is applied at a temperature of 160°C. The fast cooling of the adhesive serves for the initial handling strength and the curing with moisture of the air in a second step results in an elastomer, which cannot be melted anymore.
Thanks to the high initial strength, the modules can be processed immediately. Time-consuming process steps with curing conveyor lines or buffer zones are not necessary anymore. The photovoltaic modules can be rotated for flashing or vertically stacked immediately after bonding of the junction box.
In comparison to one- and two-component silicones or other adhesive technologies, SikaMelt®-9185 IA requires less material usage and offers an improved mechanical performance.



Junction box bonding



FEATURES AND BENEFITS

- Immediate handling
- No curing or buffer zone required
- Up to 50% less adhesive required
- Excellent adhesion on non-polar substrates
- Isocyanate-free

Packaging Information	
Hobbock	15 Kg

Technical Data	
Chemical base	Polyolefin reactive hot melt
Color	Yellow
Cure mechanism	Moisture curing
Density	0,88 Kg/l
Solids content	100%
Viscosity at 140°C	10.000 mPas
Application temperature	140 - 180°C
Open time	45 sec
Green strength	1,1 N/mm²
Curing time to final strength	20 h

Our most current General Sales Conditions shall apply.
Please consult the Data Sheet prior to any use and processing.

SIKA SERVICES AG
Tueffenwies 16
8048 Zurich
Switzerland

Contact
Tel: +41 58 436 40 40
Fax: +41 58 436 55 30
www.sika.com/solar

BUILDING TRUST